

WHAT IS CLAIMED IS:

1. An electronic component to be mounted on a circuit board comprising:

5 a first substrate having an electronic circuit device and an electrode pad on one main surface of said first substrate in electrical connection with said electronic circuit device;

10 a sealing wall whose one face is closely adhered to said one main surface of said first substrate, said sealing wall being configured to enclose said electronic circuit device with said electrode pad arranged outside of said sealing wall;

a second substrate closely adhered to the other face of said sealing wall;

15 an opening formed in said second substrate at a site confronting said electrode pad; and

an electrically conductive member extending through the interior of said opening for electrical connection with said electrode pad.

20 2. An electronic component according to claim 1, wherein said electrically conductive member comprises a bump disposed on said electrode pad.

25 3. An electronic component according to claim 1, wherein said electrically conductive member comprises:

a first bump disposed on said electrode pad for electrical connection with said electrode pad; and

a second bump disposed on top of said first bump for electrical and physical connection with said circuit board.

4. An electronic component according to claim 1, wherein
5 said electrically conductive member comprises:

a first bump disposed on said electrode pad for electrical connection with said electrode pad; and

a second bump disposed on top of said first bump for electrical and physical connection with said circuit board;

- 10 said first bump being made of gold, said second bump being made of solder.

5. An electronic component according to claim 1, wherein
said second substrate has a second sealing wall around said
15 opening configured to enclose said electrically conductive member.

6. An electronic component according to claim 1, wherein
said second substrate has a second sealing wall around said
opening configured to enclose said electrically conductive member,
20 said second sealing wall being made of the same material as that of said first sealing wall.

7. An electronic component according to claim 1, wherein
said electrically conductive member comprises:
25 a first electrically conductive member disposed on an inner wall of said opening for being electrically and physically connectable to said circuit board; and

a second electrically conductive member disposed on said electrode pad for being electrically connected with said first electrically conductive member and with said electrode pad.

- 5 8. An electronic component according to claim 1, wherein said electrically conductive member comprises:

a first electrically conductive member disposed on an inner wall of said opening for being electrically and physically connectable to said circuit board; and

- 10 a second electrically conductive member disposed on said electrode pad for being electrically connected to said first electrically conductive member and to said electrode pad; and wherein

said second substrate is a multi-layer substrate carrying one
15 or more circuit elements thereon.

9. An electronic component according to claim 1, wherein said sealing wall is made of an insulating material, said material having an adhesion to at least one of said first substrate
20 and said second substrate.

10. An electronic component according to claim 1, wherein said sealing wall is made of a material selected from a group consisting of glass, polyimide resin and epoxy resin.

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11. An electronic component according to claim 1, wherein said electronic circuit device is a surface acoustic wave

device.

12. An electronic component according to claim 1, wherein
said first and second substrates are made of the same
5 material.

13. A method of manufacturing an electronic component to be
mounted on a circuit board, said electronic component comprising:
a first substrate having an electronic circuit device and an
10 electrode pad on one main surface of said first substrate in
electrical connection with said electronic circuit device;

a sealing wall whose one face is closely adhered to said one
main surface of said first substrate, said sealing wall being
configured to enclose said electronic circuit device with said
15 electrode pad arranged outside of said sealing wall;

a second substrate closely adhered to the other face of said
sealing wall;

an opening formed in said second substrate at a site
confronting said electrode pad; and

20 an electrically conductive member extending through the
interior of said opening for allowing said electrode pad and said
circuit substrate to be electrically connectable to each other;
said method comprising:

a first step in which one faces of a plurality of sealing walls
25 are closely adhered to one main surface of said first substrate
which has a plurality of electronic circuit devices formed on said
one main surface in a plurality of circuit regions and a plurality

of electrode pads in electric connection with said plurality of electronic circuit devices, said plurality of sealing walls each configured to enclose each of said plurality of electronic circuit devices with each of said plurality of electrode pads arranged
5 outside of each of said plurality of sealing walls, and in which said second substrate is closely adhered to the other faces of said plurality of sealing walls, said second substrate having a plurality of openings at sites confronting said plurality of electrode pads;

10 a second step in which an electrically conductive member is formed on each of said plurality of electrode pads, said electrically conductive member being electrically connected with each of said plurality of electrode pads; and

15 a third step in which said first substrate, together with said second substrate, is severed for each of said plurality of circuit regions, to obtain a plurality of electronic components.

14. A method of manufacturing an electronic component according to claim 13, wherein

20 said first step includes a step in which said plurality of sealing walls are closely adhered to said first substrate after formation of said plurality of sealing walls onto said second substrate.

25 15. A method of manufacturing an electronic component according to claim 13, wherein

said first step includes a step in which said plurality of sealing walls are closely adhered to said second substrate after

formation of said plurality of sealing walls onto said first substrate.

16. A method of manufacturing an electronic component according
5 to claim 13, wherein

said second step includes a step in which said electrically conductive member is formed on each of said plurality of electrode pads through a corresponding one of said plurality of openings.

10 17. A method of manufacturing an electronic component according to claim 13, wherein

said electrically conductive member comprises a bump.

18. A method of manufacturing an electronic component according
15 to claim 13, wherein

said electrically conductive member comprises:

a first bump disposed on each of said plurality of electrode pads for electrical connection with said each of said plurality of electrode pads; and

20 a second bump disposed on top of said first bump for electrical and physical connection with said circuit board; and wherein

said second step includes a step in which said first bump is formed on each of said plurality of electrode pads through a corresponding one of said plurality of openings, after which said
25 second bump is formed on top of said first bump.

19. A method of manufacturing an electronic component according

to claim 13, wherein

a first electrically conductive member is previously formed on an inner wall of each of said plurality of openings, said first electrically conductive member being electrically connectable to
5 said circuit board, and wherein

said second step includes a step in which a second electrically conductive member is formed on each of said plurality of electrode pads, said second electrically conductive member electrically connecting said first electrically conductive member
10 and each of said plurality of electrode pads.

20. A method of manufacturing an electronic component according to claim 13, wherein

said second step is carried out after said first step.